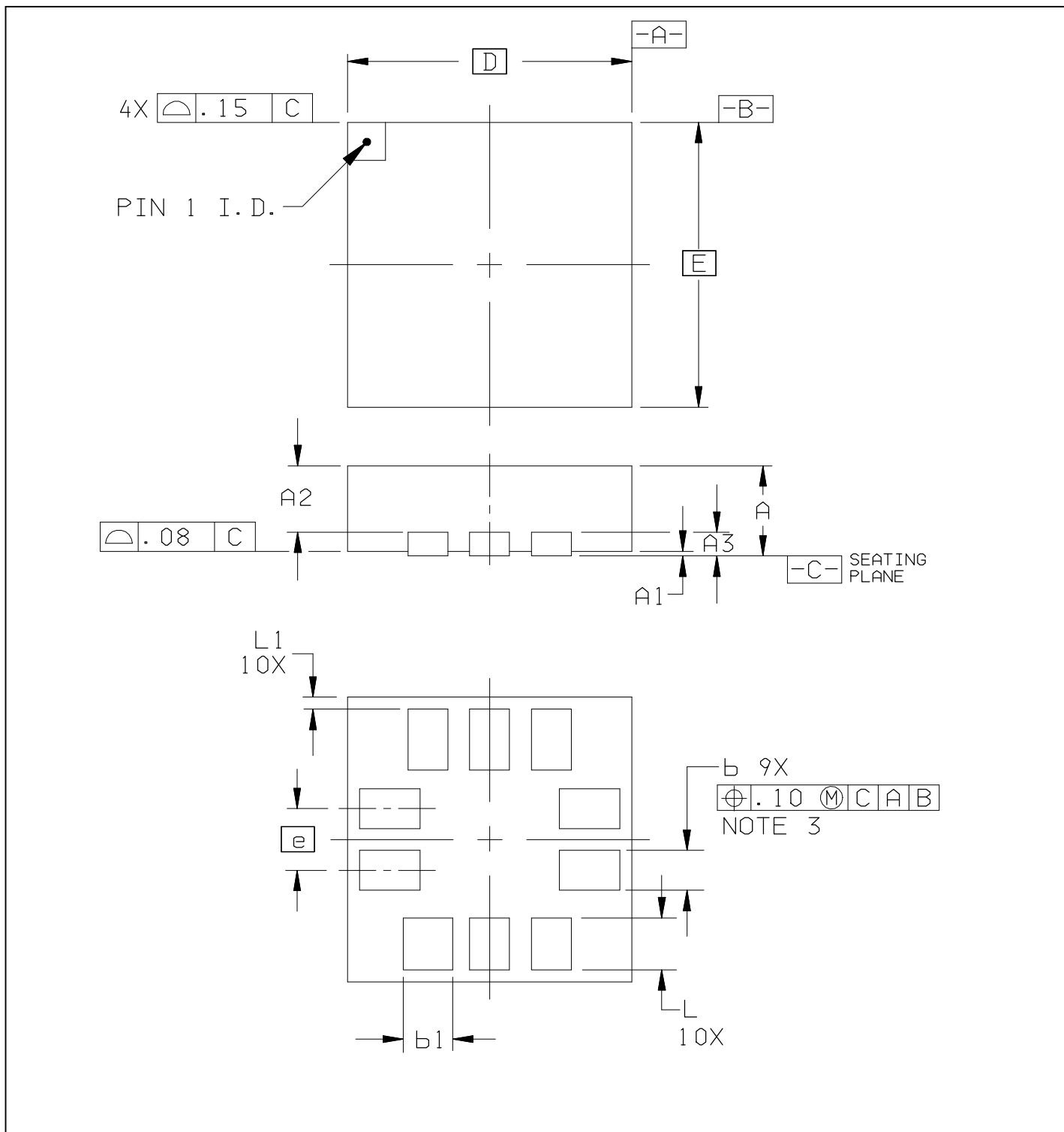



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CASE NO.	501-02
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	10 PIN QFN: 3.0X3.0MM 0.65 PITCH



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NOTES:

1. DIMENSIONING AND TOLERANCING PER Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION  $b$  APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.25 AND 0.30MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. 501-01 OBSOLETE, NEW STANDARD IS -02.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.800	1.000		
A1	0.000	0.050		
A2	0.600	0.800		
A3	0.203	REF		
D	3.000	BSC		
E	3.000	BSC		
$b$	0.371	0.421		
$b1$	0.498	0.548		
$e$	0.650	BSC		
L	0.523	0.673		
L1	0.000	0.127		

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ISSUE	REVISION	COORD/ DATE
0	RELEASED FOR PRODUCTION. REQ BY S. BLACK	FB 23 APR 02
A	ADDED PIN 1 I.D. ADDED BASIC DIM BOXES TO A, B & G. REQ. BY K. KIME	ME 16 AUG 02
B	UPDATED DIM e WAS: 0.597-0.697 REQ. BY K. KIME	ME 20 Nov 2002